



Material Content Data Sheet



Sales Product Name		IPB160N04S4-H1		Issued		22. October 2018		
MA#		MA001910702						
Package		PG-TO263-7-3		Weight*		1524.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.138	0.34	0.34	3370	3370
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	iron	7439-89-6	0.803	0.05		527	
	non noble metal	copper	7440-50-8	801.714	52.57	52.64	525921	526606
	non noble metal	aluminium	7429-90-5	11.674	0.77	0.77	7658	7658
wire	non noble metal	aluminium	7429-90-5	11.674	0.77	0.77	7658	7658
encapsulation	organic material	carbon black	1333-86-4	8.729	0.57		5726	
	plastics	epoxy resin	-	96.020	6.30		62989	
	inorganic material	silicondioxide	60676-86-0	477.189	31.30	38.17	313035	381750
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8080	8080
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	177	178
solder	non noble metal	tin	7440-31-5	0.079	0.01		52	
	noble metal	silver	7440-22-4	0.099	0.01		65	
	non noble metal	lead	7439-92-1	3.776	0.25	0.27	2477	2594
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		70	
	non noble metal	copper	7440-50-8	106.210	6.97	6.98	69673	69764
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com